

RD51

Development of MicroPattern Gaseous Detector Technologies

11/9/2019 – 139th LHCC Meeting - OPEN Session

Silvia Dalla Torre, INFN - Trieste
on behalf of the RD51 Collaboration

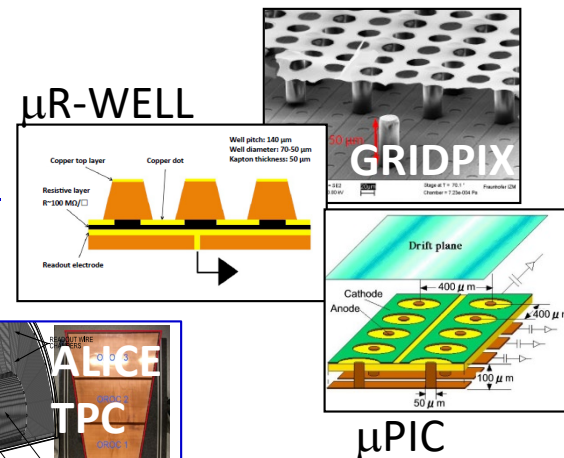
The whole matter illustrate by examples
(a fully comprehensive review is impossible)

RD51- Mission and achievements

- **Support to the development of MPGDs and dissemination of these technologies (by examples)**

DEVELOPMENT

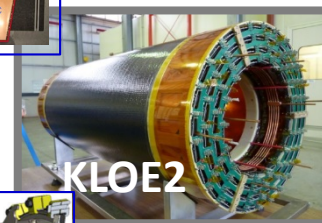
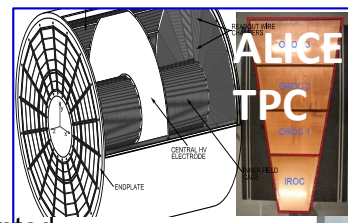
- **Consolidation of the better established technologies**
 - GEM: single mask for large size; mechanical stretching for mass production
 - MICROMEGAS: resistive anode for reliability of large size
- **Novel architectures**
 - μ PIC, μ R-WELL, GRIDPIX, hybrids, ...



DISSEMINATION by recent examples

In HEP

- ALICE, TPC read-out, 130 m² to be instrumented
- ATLAS, small wheels, 1200 m² to be instrumented
- CMS, forward detectors, 1000 m² of GEM foils to be instrumented
- COMPASS RICH, 4.5 m² hybrid MPGDs for single photon detection
- KLOE2 & BES III, cylindrical GEMs



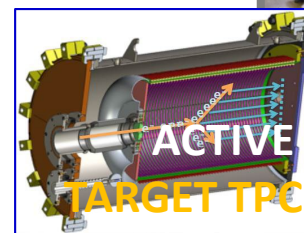
CERN

In fundamental research, beyond HEP

- LBNO-DEMO (WA105), THGEM PCBs
- read-out in low-energy nuclear physics ACTIVE TARGET TPCs

Beyond fundamental research

- n-detection: instrumenting ESS beam lines
- Muon radiography for geological and archeological studies
- Radiographies by GEMs with optical read-out: industry, homeland security

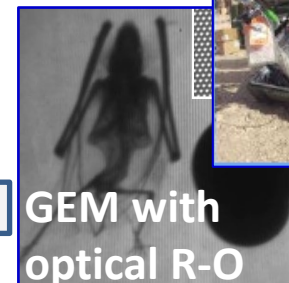


Muography of Egyptian Pyramids



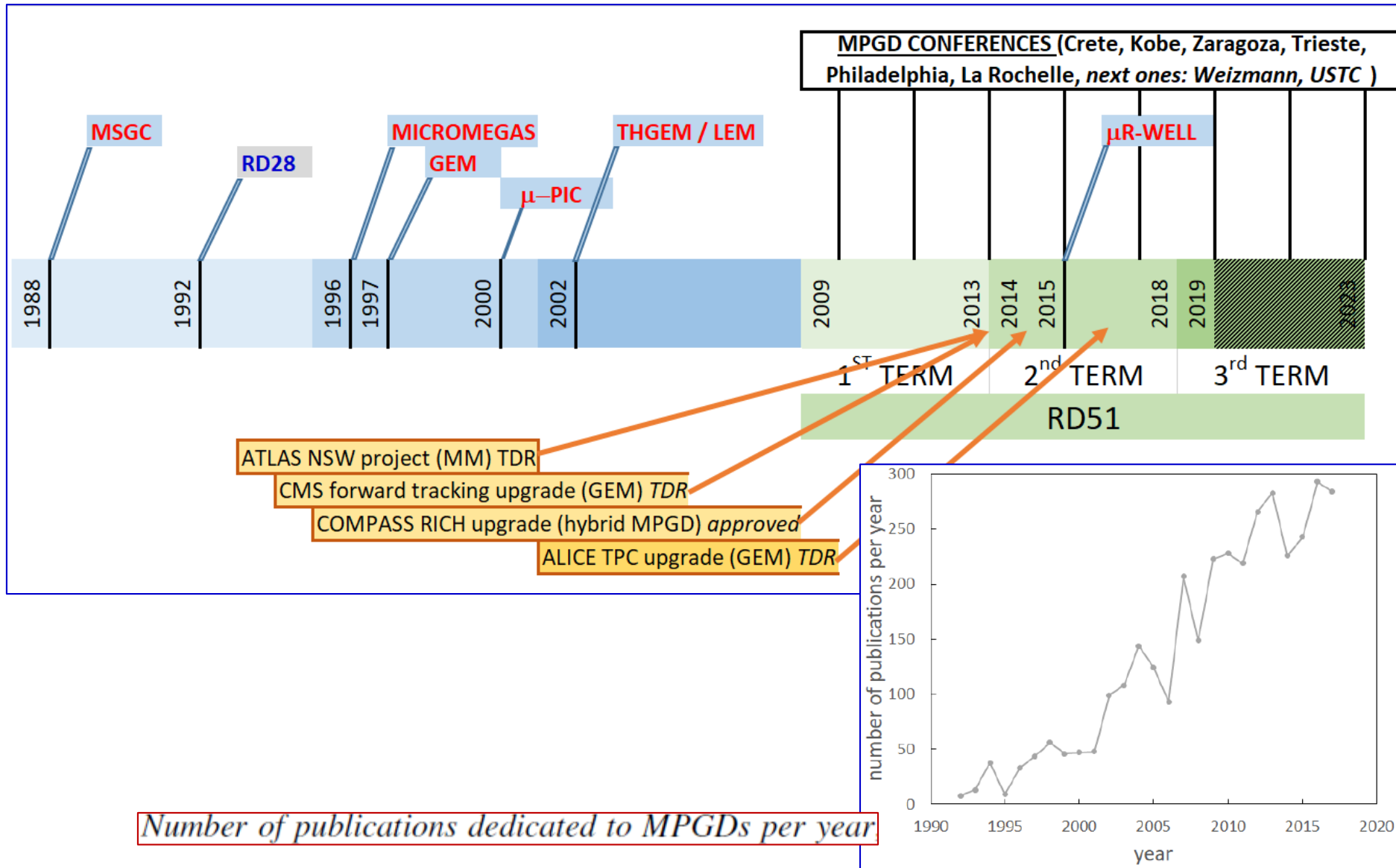
SUPPORT

- **Common infrastructures** (GDD lab, common test beam)
- **Electronics** (read-out, dedicated instrumentation)
- **Simulation** (Garfield maintenance, update and development)
- **Scientific cultural reference, know-how entry point, MPGD net-working**



GEM with optical R-O

HISTORY OF MPGDs & RD51

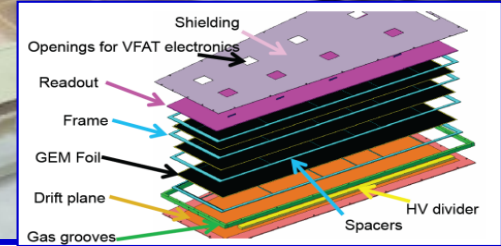


MPGDs & UPGRADE OF CERN EXPERIMENTS

CMS – forward muon spectrometer (GEM)
 Goal: $\sim 1.2 \times 2 \text{ m}^2$

1000 m^2 of GEM foils, tracking & trigger

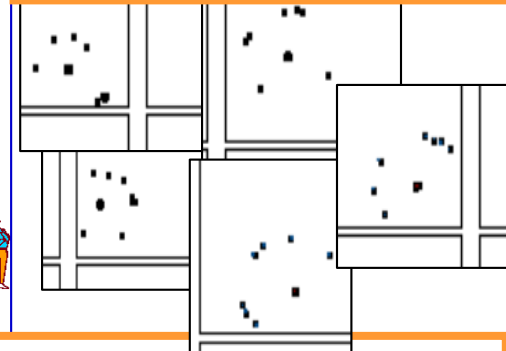
Trapezoidal GEM Prototype (99 x 45-22 cm²)



ATLAS –
 NSW project (MM)
 Detector size: $\sim 1 \times 2.5 \text{ m}^2$

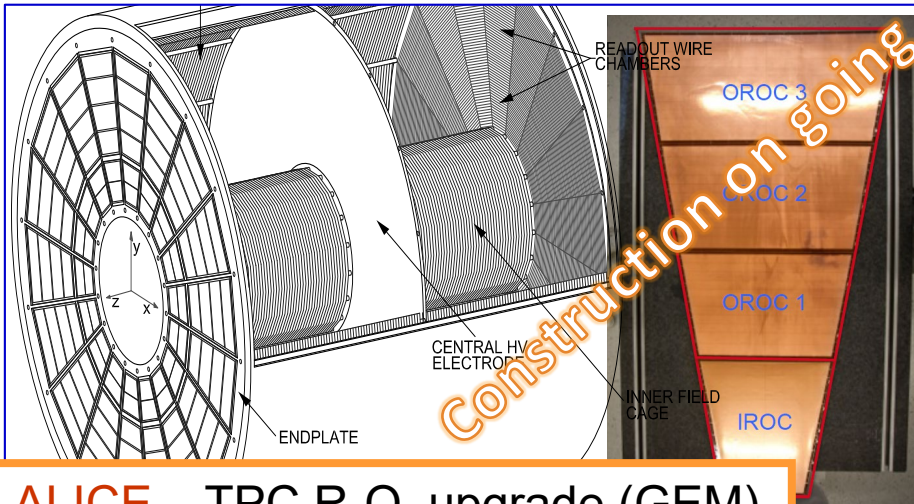
New Small Wheel,
 ATLAS muon system,
 1200 m^2 , tracking & trigger

On-line ring images



COMPASS RICH-1 upgrade
 Hybrid MPGD-based photon detectors

1.5 m^2 of MPGD multipliers (THGEM, MM)



ALICE – TPC R-O, upgrade (GEM)
 size: $\sim .9 \times 1.6 \text{ m}^2$

130 m^2 of GEM foils

RD51 – HOW ?

MPGD community integration:

90 Institutes from 25 Countries, ~500 members

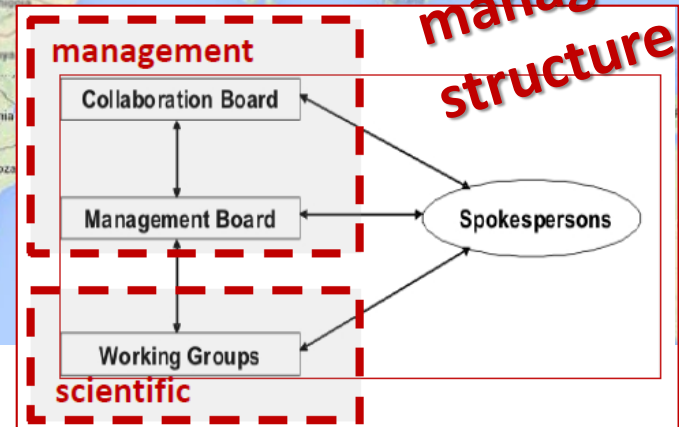
- From Europe (including Russia, Israel)
- From Japan, India, China
- From USA, South America

World-wide !

light managerial structure

Working Groups:

- **WG1 - New Structures and Technologies**
- **WG2 - Detector Physics and Performance**
- **WG3 - Training and Dissemination**
- **WG4 - Modeling of Physics Processes and Software Tools**
- **WG5 - Electronics for MPGDs**
- **WG6 - Production and Industrialization**
- **WG7 - Common Test Facilities**



MEETINGS

*2 Collaboration meetings / y
(one outside CERN)*

1-2 miniweeks / y

RD51 SUPPORT TO THE
MPGD COMMUNITY
for
DEVELOPMENT
&
DISSEMINATION

COMMON TEST BEAM FACILITY

RD51 Semi-Permanent Installation

EHN1-H4 North Area

GOLIATH

(1.5T Max, 1mt gap)

Control Room

Slow Control System (HV/LV)

Gas Zone

Storage Area

Experimental Area
(H4)

RD51 trackers

- Triple GEM
- XY strips readout, 400um pitch
- 30x10 cm²
- APV (VFAT2)
- DAQ&FE: SRS/APV (TURBOVFAT)
- XY strips readout, 250um pitch
- 96x40 cm²
- APV
- DAQ&FE: SRS/APV



RD51 Test Beams , up to 2018, typically
3 periods of 2 weeks sharing the beam with GIF++
~ 30 different groups in total with several running in parallel

Examples of detectors from different projects at the test beam facility



CMS (GEM)



WIS/A/C(WELL, THGEM)



ATLAS NSW (mm)



BESS III & SHIP (GEM)

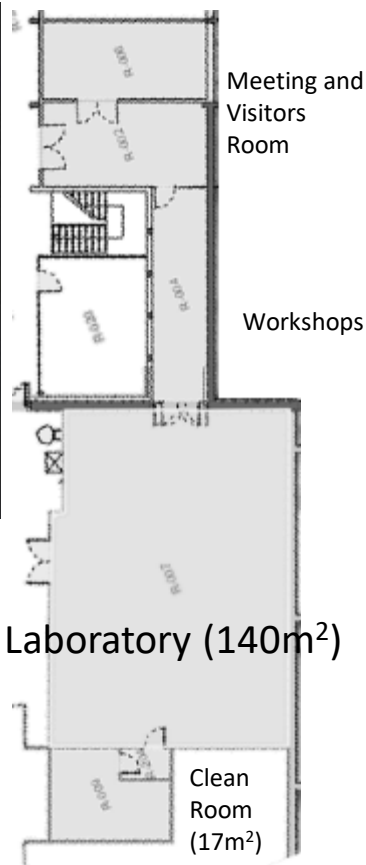


LAPP/DEM/IRFU(mm)



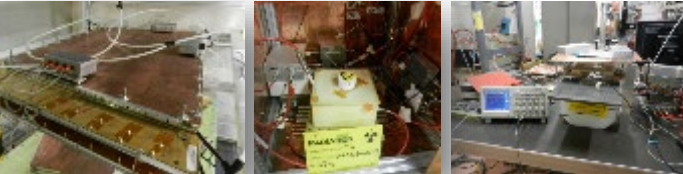
ALICE TPC (GEM and mm)

EP-DT-DD GDD Laboratory (Detector R&D) available to the RD51 Collaboration



Permanent Users (ALICE, ATLAS, ESS) station

Temporary Users Working station



Active (X-Ray) and Radioactive Sources

Cosmic Stands

Clean Room

Workshops



Optical Readout & Measurements

Vacuum Systems

Gas & Monitoring (RGA,...) Systems

MPGD Electronics



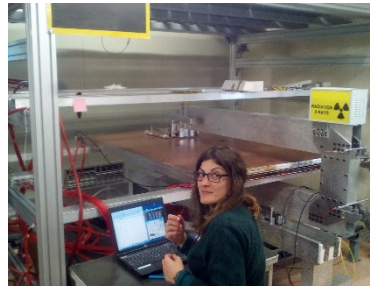
Technical support
 MPGD Detectors
 Gas system and services
 MPGD Readout electronics
 Radioactive Sources
Interface with CERN services (Thin Film and Glass Lab, MPT Workshop
 , RP, gas, metrology, irradiation facilities,...),

DIRECT SUPPORT TO EXPERIMENTS

- **Facilities Lab and Beam** (one example... ATLAS NSW micromegas)



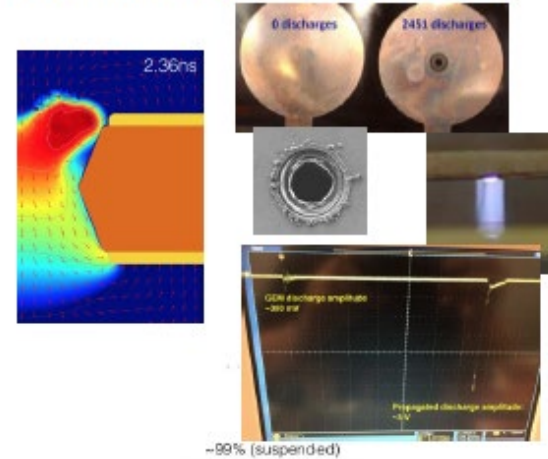
ATLAS NSW - RD51 mm trackers (GDD lab)



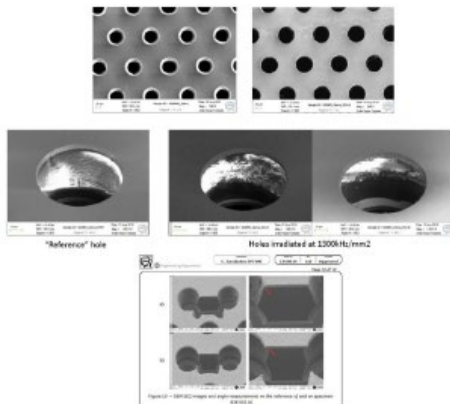
ATLAS NSW - Cosmic stands (GDD lab)

RD51/GDD Lab

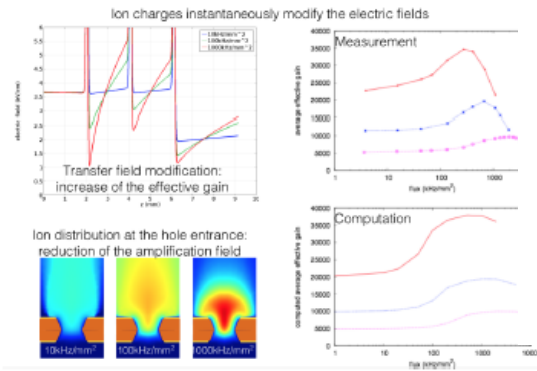
Discharge studies ALICE/CMS



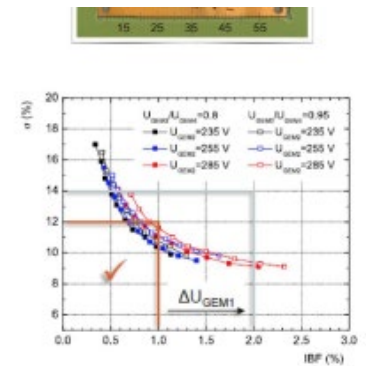
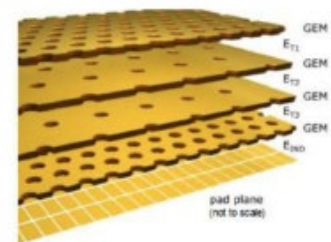
Effect of extreme operating conditions on the GEM detector components



Ion density effects in multiGEM



ALICE TPC IBF

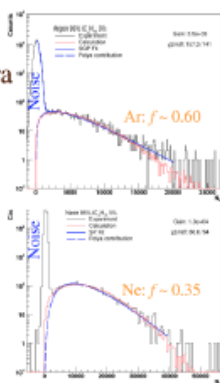
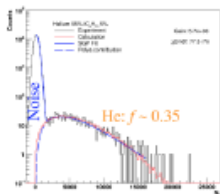


Modelling of physics processes and software tools



Single-electron spectra

blue: Poisson signal + Gaussian noise fit;
 red: Monte Carlo (Magboltz), not fits!
 Ar 95 % ^{40}Ar , 5 %, $E=28.12$ keVcm,
 Ne 95 % ^{20}Ne , 5 %, $E=26.25$ keVcm,
 He 95 % ^4He , 5 %, $E=26.25$ keVcm.



Mesh transparency

▶ Electron tracking requires improvement.

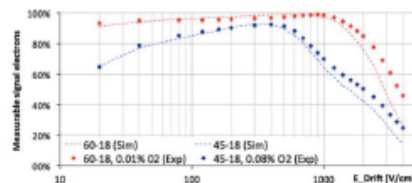


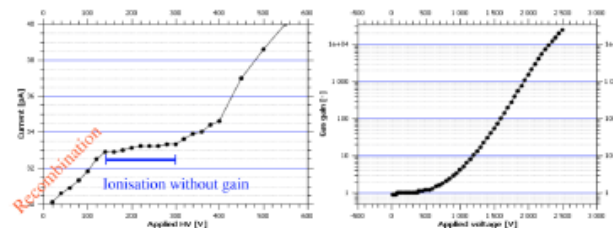
Fig. 5. Fraction of measurable signal electrons dependence on the drift field for two mesh geometries, experimental data (normalized signal strength) and simulation prediction (non-lost electrons after drift and mesh transition).

▶ [Fabian Kuger et al, 10.1016/j.nima.2015.11.011]



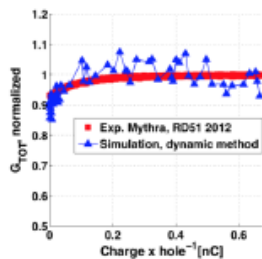
High-precision data from AGH

▶ Current reference is taken at the ionisation level.
 ▶ Main source of error: ~5 %.

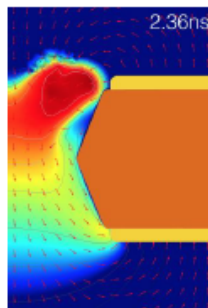


Charging-up of a GEM

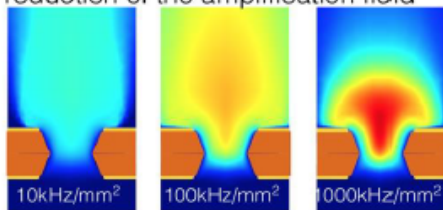
▶ Gain changes as a result of the charge deposits.
 ▶ Electron tracking to be refined.



▶ [Pedro Correia et al, 10.1088/1748-0221/9/07/P07025]



Ion distribution at the hole entrance:
 reduction of the amplification field



Gas detector simulation: new areas

- ▶ Discharges and Resistive layers.
- ▶ Ion diffusion.
- ▶ Refinement of ionisation esp. at low energy.
- ▶ Integration of boundary element methods.

ELECTRONICS: the Scalable Readout System (SRS)

CERN

SRS & APV25 FE chip

Worldwide use in the RD51 community (>2000 hybrids)

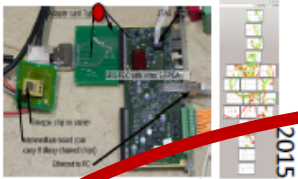
SRS+SiPM (NEXT TPC)



SRS-FEC+TOTEM DAQ

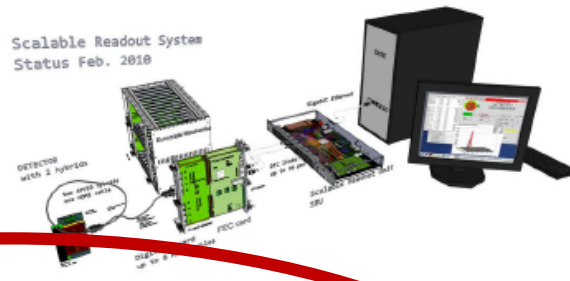


SRS+Timepix (LC-TPC) – Bonn/Desy



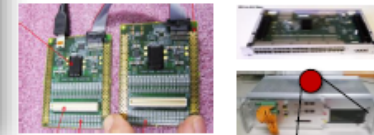
Scalable Readout System (SRS)

Scalable Readout System
Status Feb. 2010

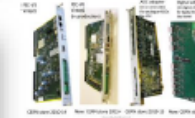


SRS: Different System

SRS for R&D on Detectors



SRS-Class: FEC and Adapter cards

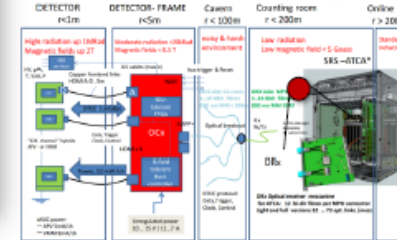


Miniboards, mini 2-FEC



SRS for experiments (ATCA)

LHC experiments: from detector to counting room



Very appealing for the future: VMM (NSW ATLAS FE chip)

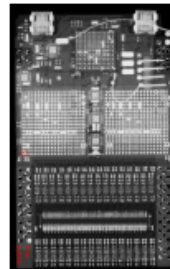
VMM-128 hybrid

VMM-128 fully operational in 2014 at RD51 cards
See report by G. Giacomelli, et al., STARBU
2" PCB revision started: 30/09/2011
30 test boards for NSW
30 test boards for RD51

Measured Power consumption 2 VMM
1.20 @ 0.25°C (1.0-40.0°C)
0.25 @ 0.25°C (0.0-20.0°C)

2 x 65 channel APV25 chips
800 STC/MSV / 2.000 MSV/20V

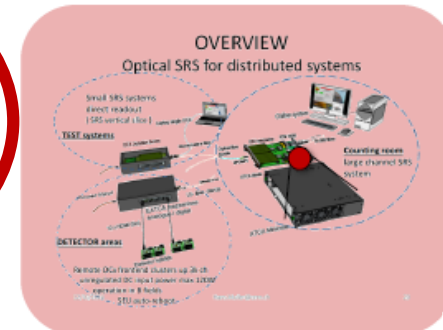
From: Setup RD51/MSV/20V



Baseline solution for RD51 SRS community.

Interest and support from ESS (European Spallation Source) and ALICE FOCAL

SRS for spatially distributed system (optical SRS)



ELECTRONICS: lab equipment for developed by the RD51 community (examples)

GAVD board and E-fuse board

36 ..54 e-fused sectors per G-AVD Unit*

(* SRS compliant)

18 HV wires to GEM sectors/board

1 Carrier for 18 e-fuses

2..3 stacked E-fuse boards

Connector & HV cable choice pending

PCB design pending

1st board by 27/03

* GAVD Unit= 1 GAVD + 1 E-fuse stack

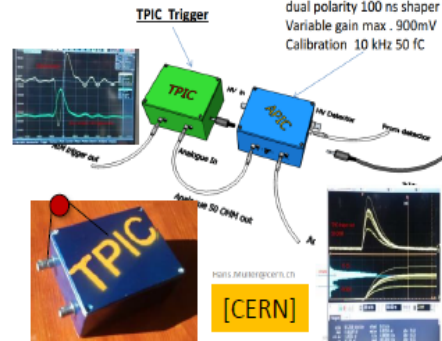
[CERN] @cern.ch

12

APIC Analogue Pickup box

(* SRS compliant)

APIC box
CSA preamplifier
dual polarity 100 ns shaper
Variable gain max . 900mV
Calibration 10 kHz 50 fC



[CERN]

QUAD MPGD signal amplifier 2 GHz, 25dB

[CERN]



a scalable HV power supply system with SoC control and real-time, high resolution I, V monitoring



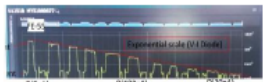
INFN-Trieste

FemtoMeter V.1.3

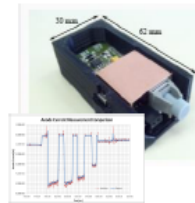


(* SRS compliant)

[CERN]



Floating Multichannel Pico Ammeter



(Optical data transmission)

[Zagreb Univ.]

MoCoS: Monitoring and control system

[CERN]

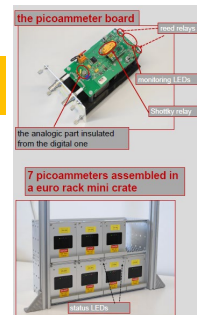


Figure 2: Scavellone detector. The portable, standalone version of the MoCoS device is housed in a 3U format case and has to be connected through all around the device.

(* SRS compliant)

a Radio-Controlled High-Voltage Insulated Picoammeter

INFN-Trieste



TECHNOLOGY: MPGD PRODUCTION @ CERN



by the MPT workshop

MPGD Projects...

•SBS tracker	GEM 600mm x 500mm
•ALICE TPC upgrade	GEM 600mm x 400mm
•CMS muon	GEM 1.2m x 450mm
•ATLAS NSW muon	Micromegas 2m x 1m
•COMPASS pixel Micromegas	GEM & Micromegas 500mm x 500mm
•BESIII	GEM 600mm x 400mm
•KLOE	GEM 700mm x 400mm
•SOLID	GEM 1.1m x 400mm
•CLAS 12	Micromegas 500mm x 500mm
•LSBB (geoscience)	Micromegas 1m x 500mm
•Prad	GEM 1.5m x 55cm
•CBM	GEM 1m x 450mm
•ASACUSA	Micromegas



New Capabilities...

	UV exposure unit limited to 2m x 0.6m → 2.2m x 1.4m	
	Resist developer limited to 0.6m width → 1.2m	
	Resist stripper " " " "	
	Copper etcher " " " "	
	Dryer " " " "	
	GEM electro etch limited to 1m → 2m	
	GEM polyimide etch limited to 1m → 2m	
	Ovens limited to 1.5m x 0.6m → 2.2m x 1.4m	
	Laminator limited to 0.6m width → 1.2m	

installation of the new infrastructure (to fabricate 2x1m² Bulk MM & 2x0.5m² GEM) COMPLETED



Construction of the new workshop's building:



Start : beginning 2012
End: end 2017

CERN Building 107

+ support to novel R&D

TECHNOLOGY: INDUSTRIALIZATION

Technology Industrialization → transfer “know-how” from CERN workshop to industrial partners

GEM Technology (contacts)

- Mecharonix (Korea, Seoul)
- Tech-ETCH (USA, Boston)
- Scienergy (Japan, Tokyo)
- TECHTRA (Poland, Wroclaw)

THGEM Technology (contacts):

- ELTOS S.p.A. (Italy),
- PRINT ELECTRONICS

GEM Industrialization Status (today):

TECH-ETCH

- Single Mask process fully understood. Many 10cm x 10cm produced and characterized.
- 40cm x 40cm GEM successfully produced
- CMS GE1/1 size of 1m x 0.5m started

TECHTRA

- Production Line Operational
- Stable process for 10cm x 10cm
- Single Mask process completely understood – 10cm x 10cm produced
- 30cm x 30cm Single Mask Produced

MECARO

- 10cm x 10cm double mask produced and tested
- 30cm x 30cm double mask under evaluation @ CERN
- CMS GE1/1 size of 1m x 0.5m

Regularly producing
for CERN store

Capability to
produce CMS
GE1/1 foils

GEM Licenses signed by:

- Mecharonics, 21/05/2013
- TECH-Etch, 06/03/2013
- China IAE, 10/01/2012
- SciEnergy, 06/04/2009
- Techtra, 09/02/2009
- CDT, 25/08/2008
- PGE, 09/07/2007

MicroMegas Technology(contacts):

- ELTOS S.p.A. (Italy)
- TRIANGLE LABS(USA, Nevada)
- SOMACIS (Italy, Castelfidardo)
- ELVIA (France, CHOLET)

MICROMEAS industrialization status (today):

ELVIA

- Bulk MM detectors are routinely produced with size up to 50x50cm²
- production for ATLAS NSW started

ELTOS

- Several small-size Bulk MM detectors produced
- production for ATLAS NSW started

THGEM industrialization status (today):

ELTOS

- THGEM for COMPASS RICH upgrade (final polishing in house)
- LEMs for LBNO-DEMO

The long-lasting
TT effort

MPGD TT today

CULTURAL NET-WORK, DISSEMINATION & TRAINING

RD51 schools

GEM & Micromegas detector design & assembly training: Lecture Session - Practical sessions
 15 February 2010 from 08:00 to 20:00 (Europe/CEST)
 CERN (513) - 634

<http://indico.cern.ch/event/20797/>
<http://indico.cern.ch/event/20813/>



MPGD assembly - 2009

RD51 Simulation School
 12-13 November 2011
 CERN

<http://indico.cern.ch/event/150634/session/16a/attachments/16a/16a.pdf>



MPGD Simulation - 2011

RD51 Electronics school
 12-13 November 2014
 CERN

<http://indico.cern.ch/event/281117/>



MPGD Electronics - 2014

XII ICFA School (Bogota, Colombia) - 2013



Danube School on Instrumentation - 2014 in Elementary Particle & Nuclear Physics (Novi Sad Serbia)



RD51 MPGD Lectures:

MPGD students lectures (1 week)
 at the International Workshop on
 Advance Detectors & RD51 CM in
 Kolkata - 2014



Open Lectures Signal generation, modelling and processing- 2017

RD51 Open Lectures: Signal generation, modelling and processing

W. Riegler, R. Veenhof, F. Resnati, S. Tzamarias

Purpose of the lectures is to discuss new developments on the methods and tools used to describe the signal generating processes as well as techniques of analysing data of gaseous detectors. The lectures are geared towards people who are doing, or intend to do, research and developments on gas-based detectors but are also open to anyone interested on the subject.

Please, fill the registration to the Open Lectures (right panel) in particular if you are planning to follow them in person at CERN.

Lectures will be broadcasted via Vidyo.

Access to the lectures is free. Certificate of Attendance will be provided under request.



MicroPattern Gaseous Detectors Conference 2019

Previous conferences:
 MPGD2009, Crete, Greece
 MPGD2011, Kobe, Japan
 MPGD2013, Zaragoza, Spain
 MPGD2015, Trieste, Italy
 MPGD2017, Philadelphia, USA

Next conferences:
 MPGD2021, Weizmann, Israel
 MPGD2023, USTC, China

CULTURAL NET-WORK: special events

Academia-Industry Matching Events (understanding requirements, applications, approaching new communities and technologies)

Academia-Industry Matching Event
Special Workshop on Neutron Detection with MPGDs

16-15-13
CERN
RD51

Neutron Detection 1st - 2013

HEP Tech
Making HEP technologies transferable
Technology Transfer opportunities

Academia-Industry Matching Event
Second Special Workshop on Neutron Detection with MPGDs

16-17-13
CERN
RD51

Neutron Detection 2nd - 2013

HEP Tech
Making HEP technologies transferable
Technology Transfer opportunities

RD51 Academia-Industry Matching Event
Special Workshop on Photon Detection with MPGDs

19-21-13
CERN
RD51

Photon Detection - 2015

HEP Tech
Making HEP technologies transferable
Technology Transfer opportunities

HEP Tech GSI enterprise europe network HESSEN TRADE & INVEST

MATCHING EVENT
Academia-Industry Matching Event
From Material to Innovation

Academia and Industry coming together to identify innovative synergies between the broad fields of High-Energy Physics (HEP) and Nanotechnology. This event will bring together nanotechnology and high-energy physics researchers and industrialists to:

- Showcase new developments in nanotechnology and HEP
- Address the needs of industry
- Provide an opportunity for collaborative R&D and technology transfer partnerships

Organizing Committee: Tiago Rodrigues de Araujo (CERN), Martina Bauer (GSI), Jerome Beaucour (ILL), Tatiana Correia (KTN), Andrea Crocini (EPFL), Tobias Engert (GSI), Jean-Marie Le Goff (CERN), Symeon Kokovidis (CERN), Antonio de Valladares Pacheco (KTN/HEPTech), Leszek Ropelewski (CERN/RD51), Jaime Segura (ILL), Aljoja Surwicz (GSI), Christina Trautmann (GSI)

20-21 October 2016
GSI Helmholtzzentrum für Schwerionenforschung,
Darmstadt, Germany
<http://rd51.cern.ch/rd512016/>

EPFL ILL KTN HESSEN TRADE & INVEST NANORA Nano Regions Alliance

MPGD Applications Beyond Fundamental Science
and the 18th RD51 Collaboration Meeting, Aveiro, Portugal

RD51

Academia-industry matching events



RD51 Collaboration Meeting and the "MPGD Stability" workshop Munich 18-22 June 2018

Workshop on Resistive Coatings for Gaseous Detectors

13 May 2019, 09:00 → 14 May 2019, 18:00 Europe/Rome

Aula Multimediale (INFN Bari)

Piet Omer J Verwilligen (BA)

Bari (Italy), 13-14 may 2019

WORKSHOP on specific aspects

TUESDAY, 21 FEBRUARY

**Precise Timing Workshop
CERN, 21-22 February 2017**

13:00 Precise timing workshop

09:00 Welcome

This workshop is intended to address the needs of a rapidly developing interest group in RD51 for a results from the RD51 PICOSEC project demonstrate feasibility of MPGD-based timing devices in the

CULTURAL NET-WORK: collaborative effort

Transversal collaborations among groups from different countries, experiments, physics areas of interest encouraged and supported by RD51

(2019)

Discharge Consortium in quest for Spark-Less-Avalanche-Microstructures

Pixelated resistive bulk Micromegas with integrated electronics

Resistive materials and resistive-MPGD concepts & technologies

(2018)

Modular & General purpose Ultra Low Mass GEM Based Beam Monitors

DLC based electrodes for future resistive MPGDS

Study of negative ion mobility and ion diffusion for Negative Ion TPCs

(2017)

Development of modular multilayer GEM units

(2016)

Sampling Calorimetry with Resistive Anode MPGDS (SCREAM)

New Scintillating gases and structures for next-generation scintillation-based gaseous detector

(2014)

Measurement and calculation of ion mobility of some gas mixtures of interest

Fast Timing for High-Rate Environments: A Micromegas Solution

Development of a novel Micro Pattern Gaseous Detector for Cosmic Ray Muon Tomography

RD51 & THE CERN and THE HEP CONTEXTs

RECENT DOCUMENTS BY RD51

May 2018

- “R&D PROPOSAL: RD51 Extension beyond 2018”
 - Resulted in the approval of RD51 till 2023

<https://arxiv.org/abs/1806.09955>

December 2018

- Input for the EPPSU process:
“Development of the MPGD Technologies: an overview of the CERN-RD51 Collaboration”
 - The RD51 model for detector R&D is presented

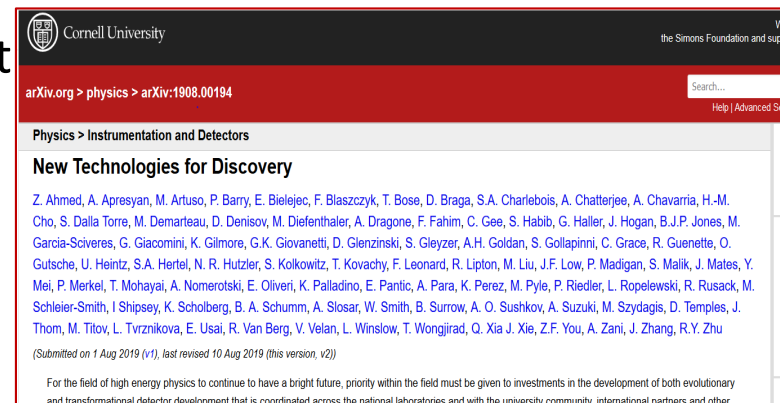
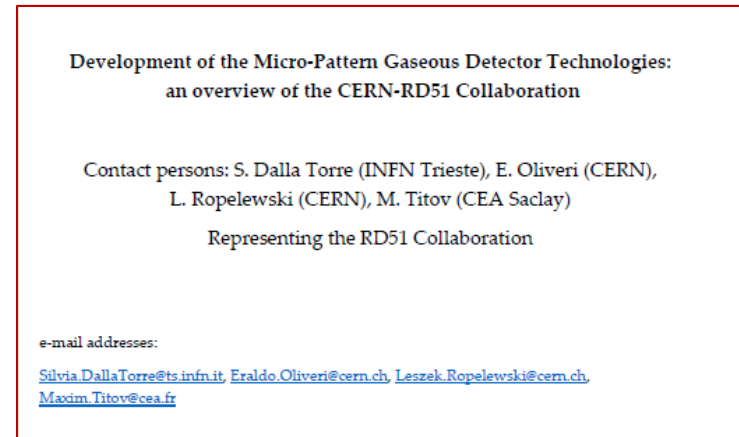
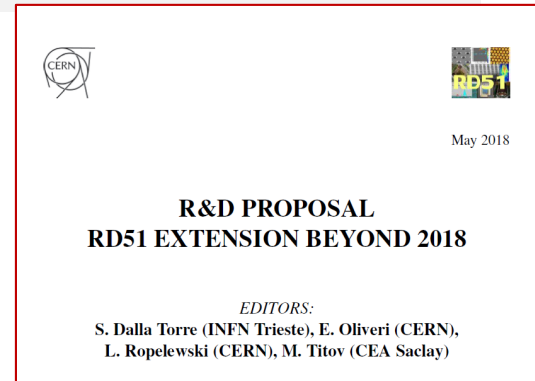
<https://indico.cern.ch/event/765096/contributions/3295721/>

Summer 2019

- Document for the US BRN (Basic Research Needs) in preparation based on CPAD report
“New Technologies For Discovery”
 - Progress of MPGDs and RD51 model

<https://arxiv.org/abs/1908.00194>

LHCC, 11 September 2019



RD51 RESULTS & MODEL RECOGNIZED WITHIN THE CERN STRATEGIC R&D PROGRAM



<https://cds.cern.ch/record/2320737/files/LHCC-SR-006.pdf>

Contents

- 1 Executive Summary
- 2 Introduction
 - 2.1 Motivations and mission of the RD51 Collaboration
 - 2.2 MPGD progress during the RD51 years: the consolidation of the existing technologies
 - 2.3 MPGD progress during the RD51 years: novel technologies
 - 2.4 MPGD progress during the RD51 years: MPGD applications
 - 2.5 MPGD progress during the RD51 years: dissemination
- 3 RD51 Legacy, Expertize and Infrastructures
 - 3.1 Community and Expertise
 - 3.2 Detector physics, simulations and software tools
 - 3.3 Electronics
 - 3.4 Workshops
 - 3.5 Common space and common test facilities
- 4 RD51 extension beyond 2018: the overall scope and objectives
 - 4.1 R&D Program on Advanced MPGD Concepts
 - 4.2 Support and Infrastructures
- 5 Requests to CERN

1. Thanks to the enormous progresses achieved during the RD51 years, MPGD are considered as key technology in the strategic EP strategic R&D programme on technologies for future experiments...

2. ... as well as the R&D frameworks, fully shared in both documents

3. R&D Programs share research lines/people on Advanced MPGD Concepts
Resistive materials and architectures (Screen printing, DLC, embedded resistors... SCREAM, mRWELL, RPWELL,...); Fast and precise timing; New materials and technologies (solid converters, manufacturing techniques,... ; Hybrid detectors (MPGD hybrids, optical readout, integrated pixel ASICs); ...



<https://lep-dep.web.cern.ch/sites/lep-dep.web.cern.ch/files/CERN-OPEN-2018-006.pdf>

- 5 Gas based detectors (WP2)
- 5.1 Introduction and overview
- 5.2 Large area gaseous detector systems
- 5.3 R&D Framework and Tools
- 5.4 Novel technologies
- 5.5 Summary
- Chapter references

RD51 & NEXT PROJECT (in preparation) for the European call “H2020 Innovation Pilot on Detector Technologies” (AIDA++)

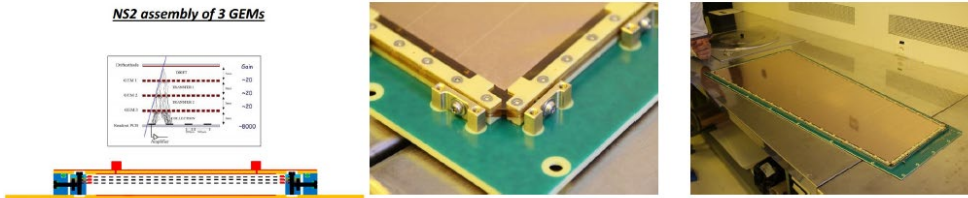
- Expressions of Interest (EoI) submitted last July
- **18 EoIs** (/162) related to MPGDs
- Signed by **23 Institutions** (/ 26) collaborating in RD51

CONSOLIDATION OF MPGD TECHNOLOGIES & NEW TECHNOLOGIES

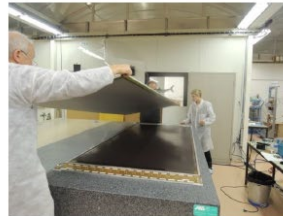
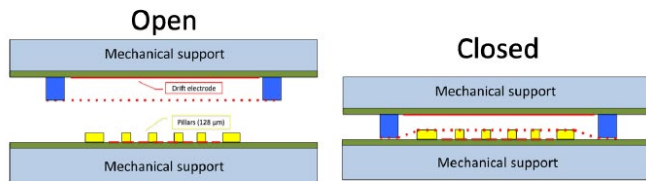
(a few examples)

GEM & MM CONSOLIDATION

GEM single mask and NoStretch-NoSpacer (NS2)

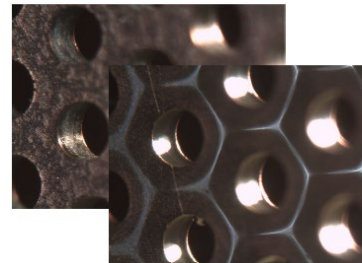


Assembly of resistive anode MMs



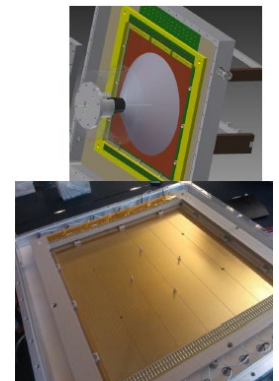
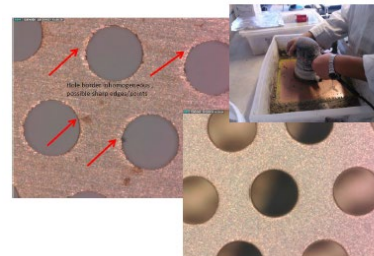
THGEM finishing

Polyurethane Treatment



Non-treated THGEM suffers from: limited max. gain, response non-uniformity and time instabilities

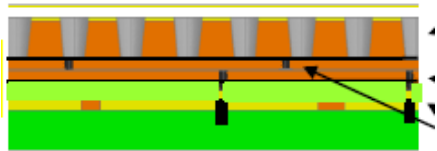
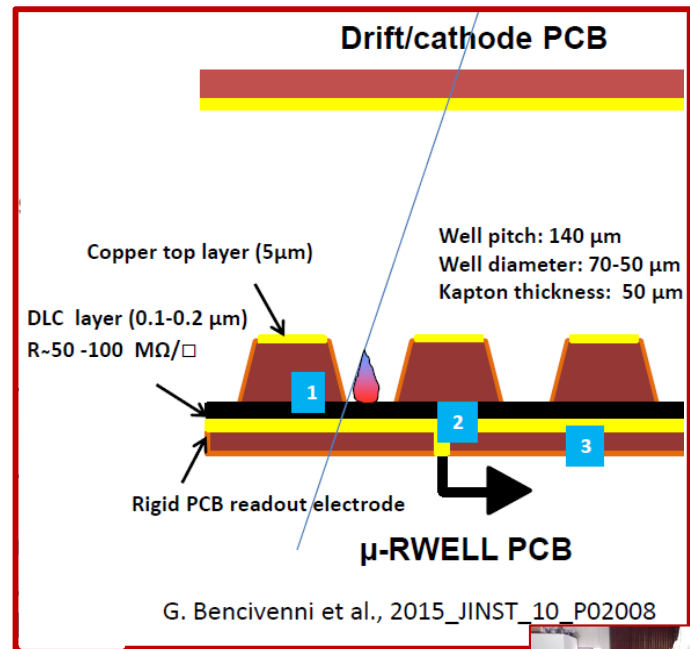
Polishing and Cleaning



μ R-WELL

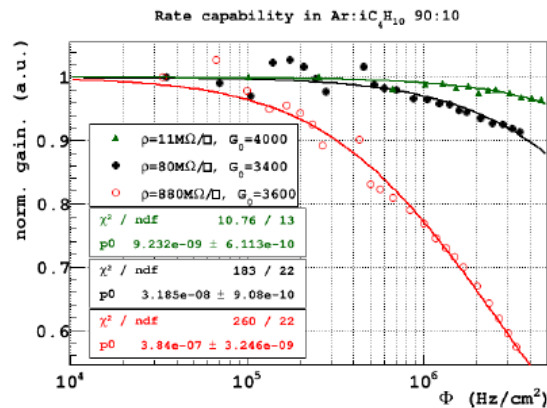
Compact, single amplification stage

- Thanks to the resistive plane:
 - very reliable
 - almost completely *discharge-free*
 - adequate for high particle rates $O(1\text{MHz}/\text{cm}^2)$ thanks to the *segmented-resistive-layer*
- performance:
 - gain $\geq 10^4$
 - rate capability $> 1 \text{ MHz}/\text{cm}^2$
 - space resolution $< 60 \mu\text{m}$
 - time resolution $< 6 \text{ ns}$



High rate version:

Double resistive layer and multiple connections



Rate capability up to $10^7 \text{ Hz}/\text{cm}^2$

Perspectives

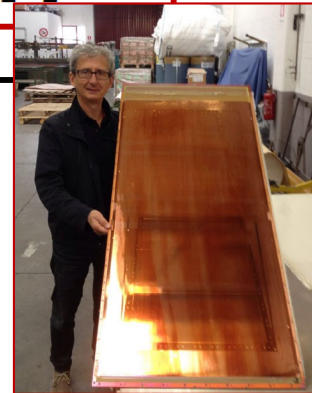
single-resistive layer (moderate-rate):

- Interest for CMS – upgrade phase 2,
Tracking at EIC

progressing towards large-size with industrial Partners

double-resistive layer (high rate):

- suitable for LHCb-Muon upgrade
- Tracking at e+e- colliders

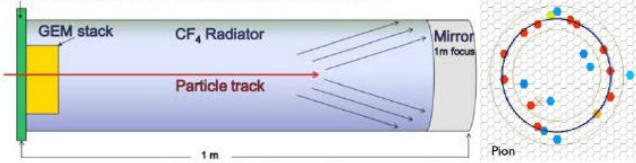


RD51 DISSEMINATION worldwide / beyond HEP

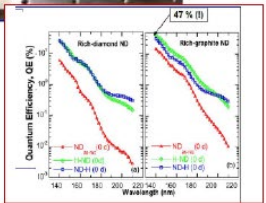
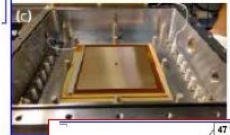
(a few examples)

MPGD R&Ds for EIC

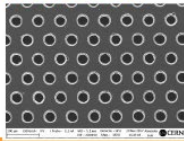
Quintuple GEM photon detector for a windowless gaseous RICH



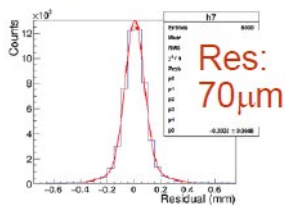
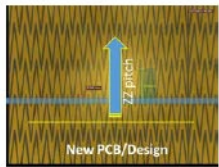
RICH r-o with hybrid MPGDs with miniaturized pads and novel nanodiamond photoconverter



Low material-budget with ultra-low mass Chromium GEM foils

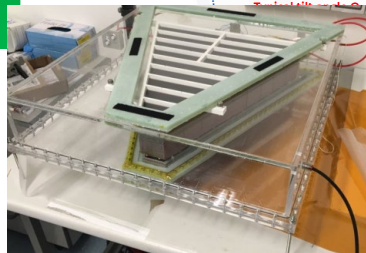
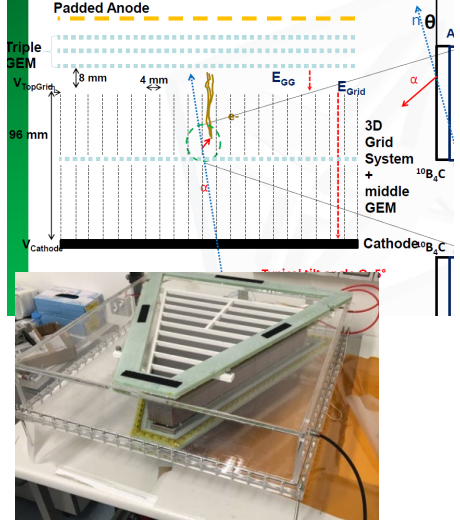


Zigzag GEM read-out for low channel count preserving fine space resolution in TPC r-o



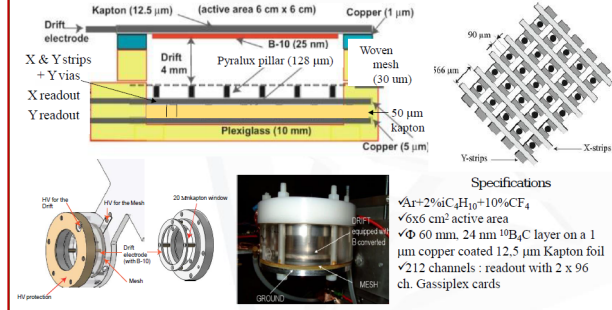
n-DETECTION by MPGDs

BAND-GEM detection principle

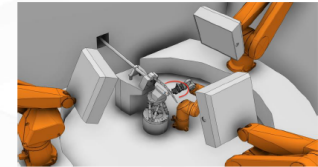
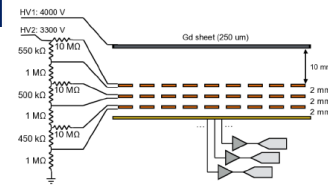


CERN/n-TOF 2D X-Y neutron beam profiler

128 μm Bulk-micromegas technology with 2D X-Y readout (CAST-like) Use of ¹⁰B(n,α)Li for up to 1 MeV neutron conversion



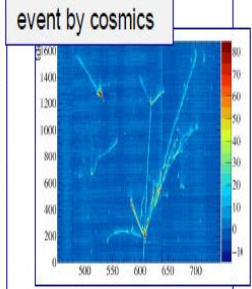
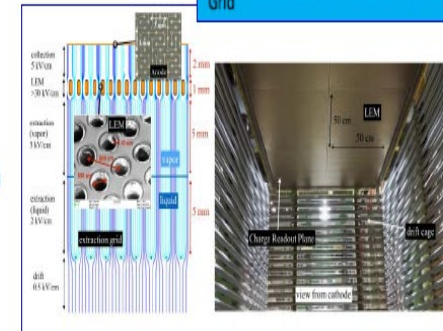
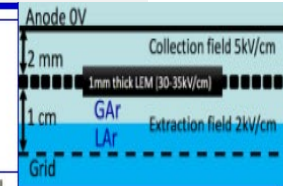
Gd-GEM for NMX @ ESS



MPGD & DETECTION OF RARE EVENTS

WA105 (3x1x1 m³ LAr prototype) (LBNO-DEMO)

- double phase for read-out by LEMs (THGEM)
- Top: 50 x 50 cm² LEMs, 2-D anode
- PMT plane, bottom



RD51 RUNNING TOWARDS THE FUTURE

(a few examples)

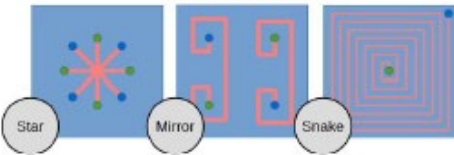
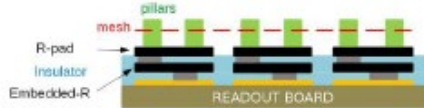
FLAGSHIP TECHNOLOGIES: resistive materials and related architectures

Pad boards

10X10 matrix of 1x1 cm² pads
Routing on the outside to a 'Gassplex' connector (96 channels)

R-structures and Bulk-Micromegas

Serigraphy and photolithography at CERN MPGD workshop

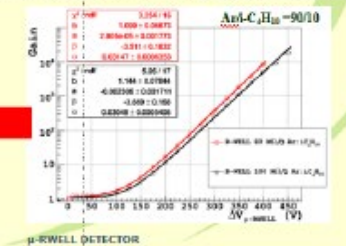
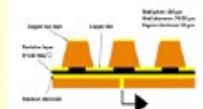


The μ -RWELL performance (I)

The prototypes have been tested with $Ar/CO_2 = 70/30$ & $Ar/C_2H_6 = 90/10$ gas mixtures and characterized by measuring the **gas gain**, **rate capability** and **discharge in current mode**.

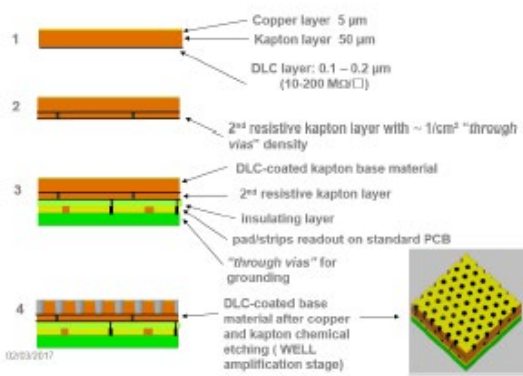
The devices has been irradiated with a collimated flux of **5.9 keV X-rays** generated by a PW2217/20 Philips Tube.

The **gain** has been measured vs **potential applied** between the **top of the electrode** of the **amplification stage** and the **resistive layer**.



GAIN UP TO 10⁴

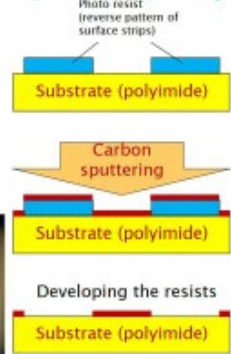
The High Rate scheme (LHCb)



Resistive electrodes with DLC

- On beginning of 2013, we have developed resistive electrodes by DLC
- Initially, it was developed for ATLAS MM resistive foils
- Fine micro-patterning (μ m order) available \rightarrow applying it for u-PIC electrodes

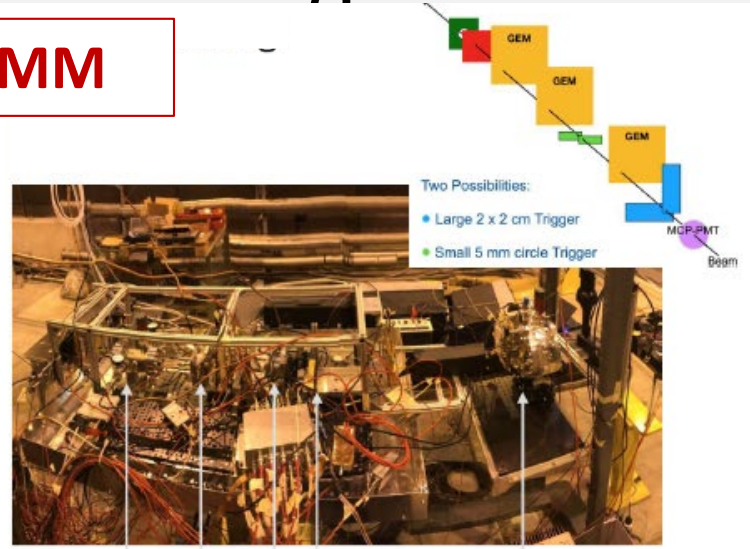
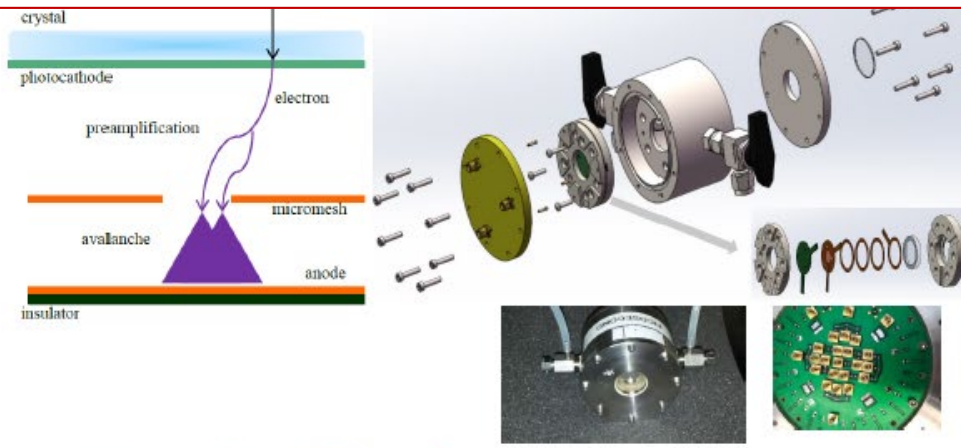
Liftoff process with sputtering



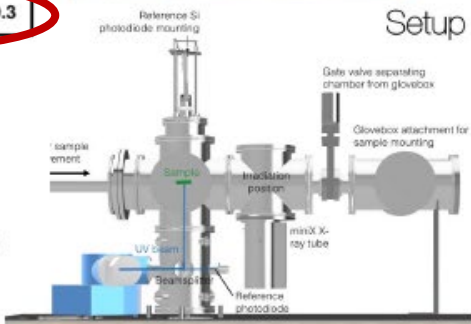
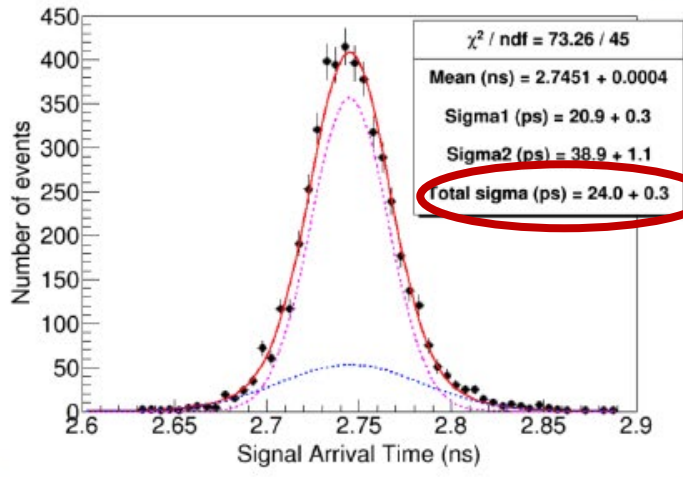
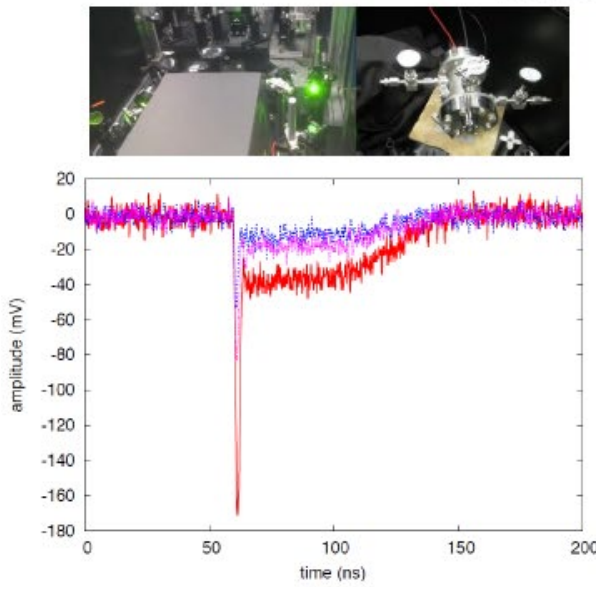
FLAGSHIP TECHNOLOGIES:

fast and precise timing

Cherenkov light + photoconverter (CsI) + MM



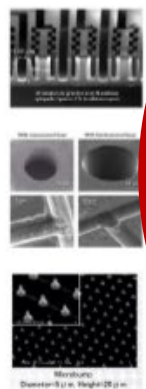
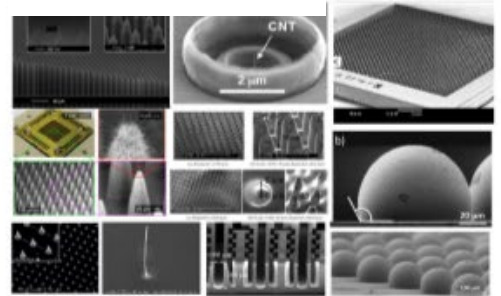
Resistive Picosec HFS Multipad



FLAGSHIP TECHNOLOGIES: new materials and technologies

Prototyping: new techniques as 3D/Ink-Jet printing, etching and laser to create novel structures will speed up and enlarge the detector prototyping capabilities.

3-D PRINTING

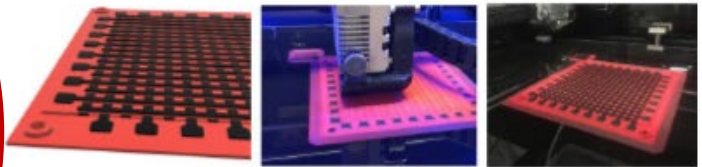


DRIE Plasma
Deep reactive-ion
etching

Laser Drilling

Super InkJet Printer

2D strip anode



2 layers of strips separated by insulating material

Bottom strips: 3mm wide at 6mm pitch
Top strips: 2mm wide at 6mm pitch

Signal feedthrough to the back for contacting

18kΩ resistance along track

Innovative photocathodes by ND powder

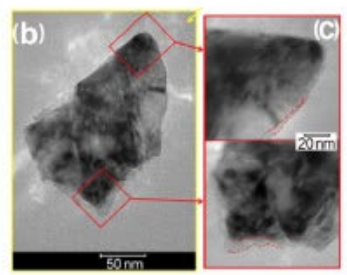
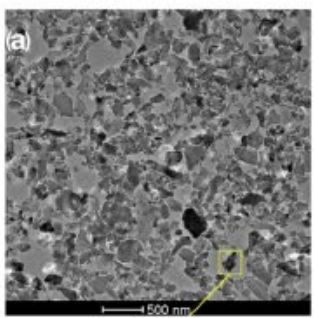
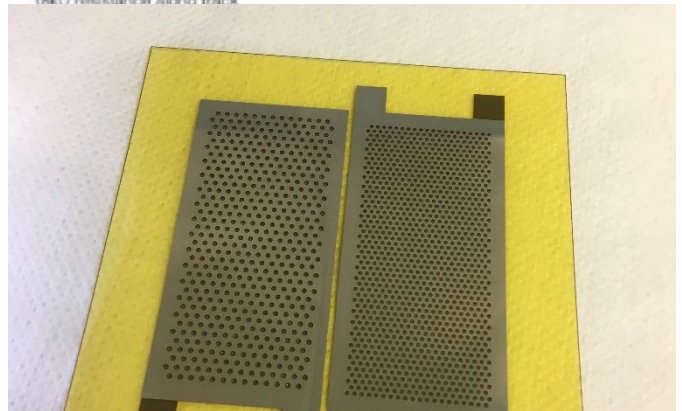


FIG. 2. TEM images of the (a) as-received nanodiamond (ND) particles, (b) a single ND particle and (c) details of the single ND particle.

Highly efficient and stable ultraviolet photocathode based on nanodiamond particles
L. Velardi, A. Valentini, and G. Cicala, Appl. Phys. Lett.108, 083503 (2016)



THGEMs by 3-D PRINTING, working !

FLAGSHIP TECHNOLOGIES: hybrid detectors

MM on a TIMEPIX detector

*InGrid & TimePix, the ultimate gaseous TPC
(H. Van Der Graaf)*

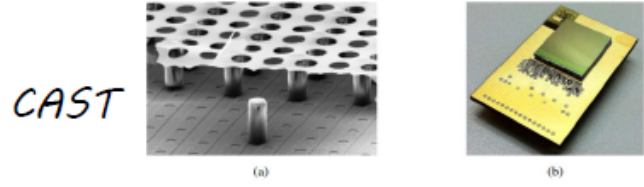
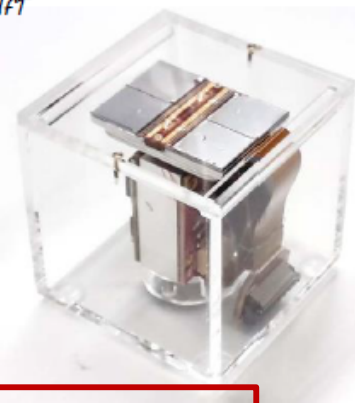


Figure 1: SEM image of an InGrid structure on top of a Timepix ASIC (a), taken from [13]. In the SEM image parts of the mesh have been removed to show the good alignment between pixels and mesh holes. And a bare Timepix ASIC on a carrier board (b).

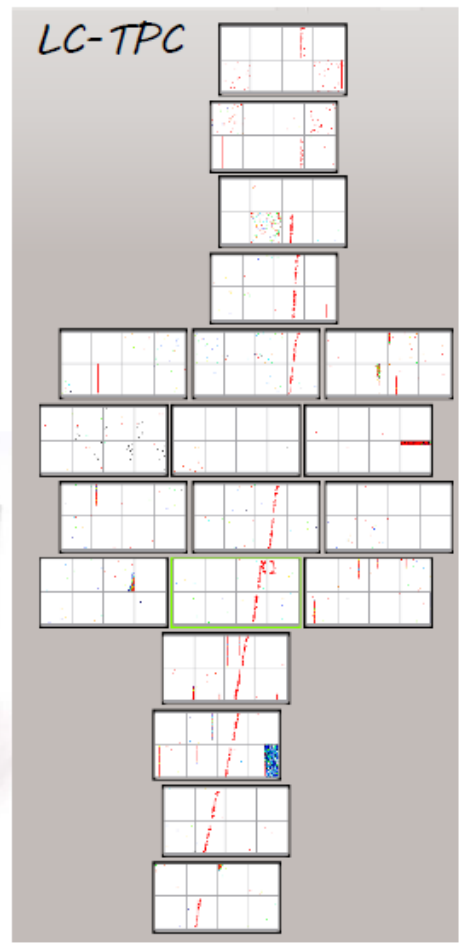
[https://cds.cern.ch/record/2025932/files/PoS\(TIPP2014\)060.pdf](https://cds.cern.ch/record/2025932/files/PoS(TIPP2014)060.pdf)

256 x 256 pixels, 55 x 55 μm pitch,
about 1.4x1.4 cm² sensitive area

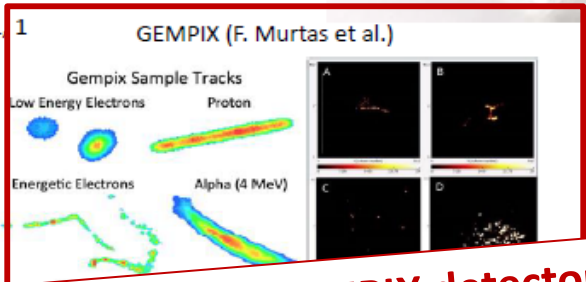
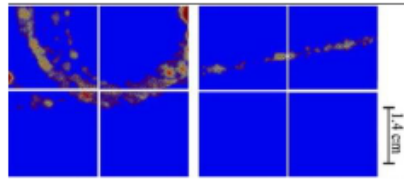
F. Hartjes,
https://agenda.linearcollider.org/event/7795/contributions/40334/attachments/32507/49403/QUAD_development.pdf



The "QUAD"



A large TPC prototype for a linear collider detector P. Schade, J. Kaminski, NIMA, 628, 1 February 2011, Pages 128-132



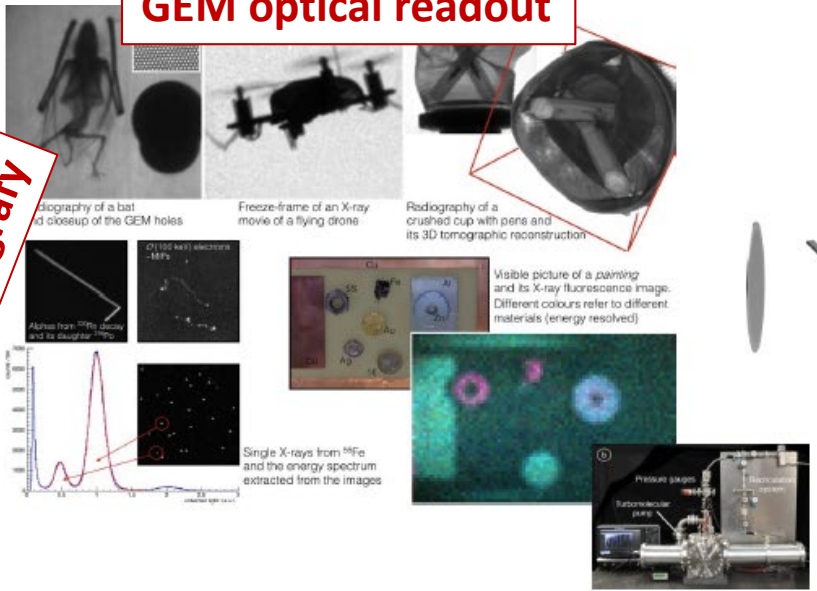
GEM on a TIMEPIX detector

J. Kaminski,
<https://indico.cern.ch/event/391665/contributions/1822/attachments/1230061/1802690/GridPix.pdf>

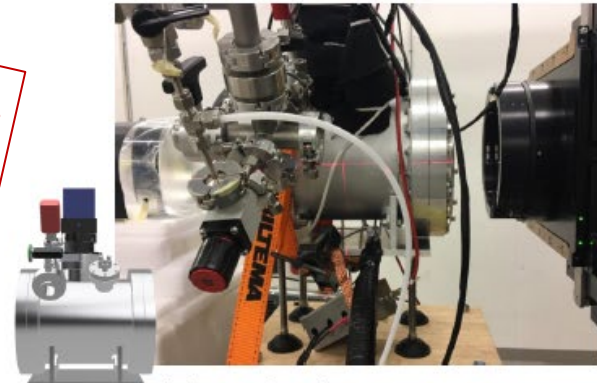
FLAGSHIP TECHNOLOGIES: hybrid detectors

GEM optical readout

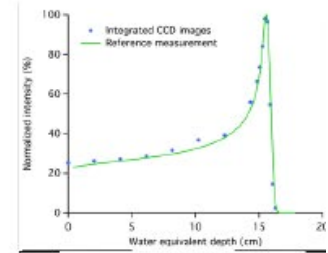
Radiography



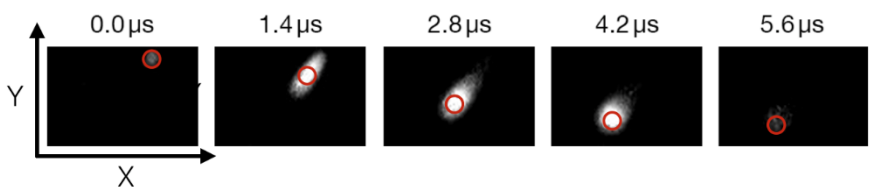
Medical application: dosimetry



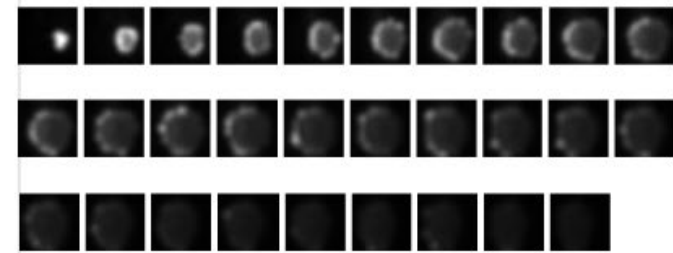
Depth dose curve



Coupled to fast camera readout: HEP applications (TPC)



Patient treatment plan



RD51 REQUESTS

RD51 REQUESTS

RD51 requests limited support from CERN facilities at existing level:

- access to the **Gaseous Detectors Development** (GDD) lab space, infrastructure and maintenance support
- **office** space and **administrative support**
- maintenance of the semi-permanent setup at the SPS H4 **test beam** line in view of 2021 (beams back !)

- continuation of the **collaborative access** to the:
 - the **Micro Pattern Technology** Workshop (EP-DT-EF MPT)
 - the **Thin Film and Glass Laboratory** (EP-DT-EF TFG)

- access to **other CERN technical facilities**, in particular:
 - Bond Laboratory (EP-DT-DD)
 - Electronics Assembly Workshop (TS-DEM-WS)
 - Materials, Metrology & Non Destructive Testing (EN-MME-MM)
 - Surface treatment, coating and chemical analysis (TE-VSC)
 - the central computing resources for MPGD simulations